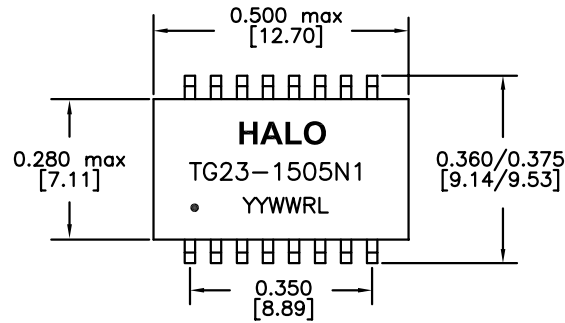
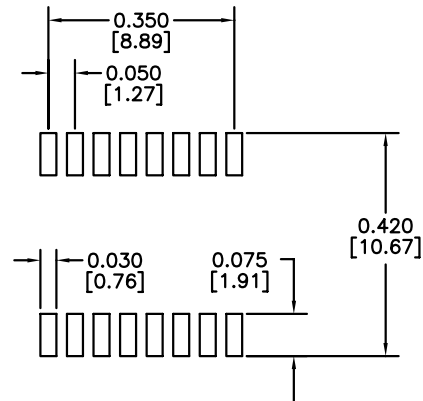


DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS

PART NO. : TG23-1505N1RL

16PIN DUAL SMT T1/E1 ISOLATION MODULE

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO REGOGNIZED

EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO

P1-3:P16-14,P6-8:P11-9 1:2.42CT±2%

OCL P1-3,P6-8 1.5mH typ

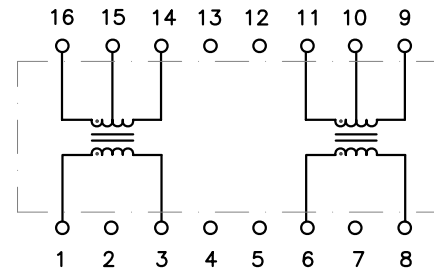
DCR P1-3,P6-8 0.8Ω max

Cw/w 35pF max

LL P1-3,P6-8 0.5μH max

CROSSTALK 0.5-5MHz -60dB typ

ISOLATION 1,500Vrms



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE SMT ISOLATION MODULE

FOR T1/E1 (1:2.42)

PART NO. TG23-1505N1RL

SCALE NONE

PAGE 1 OF 1

SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE 1505N1RL.DWG

DATE

4/13/05

10/26/10

10/26/10

REV.

A

B

C

DESC.

FIRST ISSUE

UPDATE

PROD. RELEASE

DATE

4/13/05

10/24/05

10/26/10

